

EDUCATION

Degree	Institute	CGPA	Year
M.Tech+PhD dual degree	Indian Institute of Technology, Palakkad	9.27	2022
B.Tech(Electrical and Electronics)	National Institute of Technology, Calicut	8.11	2020
Class XII	Kadambur Higher Secondary School	97.8%	2015
Class X	Kadambur Higher Secondary School	100%	2013

TECHNICAL SKILLS

- Hands on experience in Deep learning
- Hands on experience in Machine Learning
- GUI development using Object Oriented Programming
- Embedded Systems (PIC18F, Embedded C)
- Hand on experience in Data analysis using python
- Hands on experience in Data Base Management Systems
- Softwares (MPLAB X IDE, CCS studio, MATLAB Simulink, PSCAD, DSA tools)
- Programming languages (C, Python 3, MATLAB, SQL)

PROJECTS

- Developed Deep learning methods to aid the security aspects of an over current relay
- GUI developed in Python for load flow analysis
- Implemented and tested Microcontroller based over current relay
- Implemented Power Line Communication and transferred data through power line
- Implemented overcurrent relay, directional relay in MATLAB
- Developed dashboard to visualize data from a database
- Developed a GUI software for power system applications and integrated various algorithms
- Reinforcement Learning based control for controlling power flow in a simple power system

PUBLICATIONS

Accepted publications :-Thoufeer K K et al.“ BigSync: Bigdata Analytics For Synchronphasors”,IEEE,5th International Conference on Power,Control & Embedded Systems (ICPCES), January 06 - 08, 2023, Prayagraj, India

Publications under revision :-Thoufeer K K, Manas Kumar Jena, “Enhancing Security Aspect of Overcurrent Relays Against Cyberattacks”, IEEE System Journal (**Manuscript ID ISJ-RE-22-14979-R1**)

Publications under review :-Thoufeer K K, Manas Kumar Jena, “Revisiting Power Swing Blocking Schemes for Future Power Systems with High Penetration of Inverter Based Resources” IEEE System Journal (**Manuscript ID ISJ-SH-22-15192**)

Book chapter under preparation:-A book chapter on SMART METERING: INFRASTRUCTURE, METHODOLOGIES, APPLICATIONS AND CHALLENGES is under preparation. The abstract was approved.